12-10-2002

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1c912 U.S. PTO
10/308517
12/03/02

December 3, 2002

Commissioner for Patents
Washington, DC 20231

Re: Advanced Semiconductor Engineering, Inc.
Matter No. 402100
Patent Application for:
METHOD OF MANUFACTURING MULTI-CHIP STACKING

MKP
12/3/02

Dear Sir:

Please record the attached original document or copy thereof.

1. Names of conveying party:

   Jen-Kuang Fang

2. Name and address of receiving party:

   Advanced Semiconductor Engineering, Inc.

   Address: 26 Chin 3rd Road
   Nantze Export Processing Zone Kaoshiung
   Taiwan, R.O.C.

3. Nature of Conveyance: Assignment
   Execution Dates: November 22, 2002

4. This Assignment is being filed together with a new application the execution date of which is: November 22, 2002.

5. Name and address of party to whom correspondence concerning document should be mailed:

   Harold V. Stotland
   Seyfarth Shaw
   55 East Monroe Street

12/09/2002 DBYRNE 00000239 10308517
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6. Total number of applications involved: 1. 10308517

7. Total fee enclosed (37 CFR 3.41): $40.00

8. Please charge any additional fees or credit any overpayment to Deposit Account No. 19-1351.

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Date: 12/3/02

Harold V. Stotland

Total Number of Pages including Cover Sheet, Attachments, and Document: 4

HVS:pav

ASSIGNMENT

Title of Invention: METHOD OF MANUFACTURING MULTI-CHIP STACKING PACKAGE

Assignee: Advanced Semiconductor Engineering, Inc.
[Company Name]
26 Chin 3rd Road, Nantze Export Processing Zone Kaoshiung,
Kaoshiung, Taiwan, R.O.C.
[Address]

Taiwan, R.O.C.
[Place of Incorporation]

Name of Inventor and Assignor:	Date of Execution of Patent Application:
Jen-Kuang Fang	**22 November, 2002**

I, the undersigned, for good and valuable considerations to me in hand paid, the receipt and sufficiency whereof are hereby acknowledged, have sold, assigned, conveyed and set over, and do hereby sell, assign, convey and set over unto the above-identified assignee (hereinafter "Assignee"), its successors and assigns, the entire right, title and interest in and to all subject matter invented or designed by me and disclosed in the above-identified application, and any divisions and continuations thereof and in and to all Letters Patent of the United States including any reissues and extensions thereof that may be obtained therefor, and the right, where such right can be legally exercised, in its own name to apply for and obtain Letters Patent, Inventor's Certificates, Utility Models and Designs, in countries foreign to the United States, including the full right to claim for any such application the benefits of the International Convention as fully and entirely as I could have done if the application had been in my name, and the entire interest in any Letters Patent, Inventor's Certificate, Utility Model or Design which may be granted on any such application in such foreign country; and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States, and any official of any country or countries foreign to the United States whose duty it is to issue Letters Patent, Inventor's Certificates, Utility Models or Designs, on applications as aforesaid, to issue any and all Letters Patent, Inventor's Certificates, Utility Models and Designs that may be granted for said invention to ASSIGNEE, its successors and assigns.

I hereby authorize and request an attorney in Seyfarth Shaw, to insert here in parentheses the serial number ( ) and the filing date ( ) of said application when known.

And for the above-named considerations, I hereby agree that I will, without additional compensation but without cost to me, promptly communicate to Assignee, its successors and assigns, any facts known to me respecting said invention whenever requested, and testify in any legal proceedings, sign all lawful papers, execute all divisional, continuing and reissue applications for Letters Patent and assignments thereof, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, as and when requested by them, in obtaining and enforcing proper patent protection for said invention or inventions and improvements in the United States.

✓

Dated: 22 November 2002

Jen - Kuang Fang
[Signature]

Jen-Kuang Fang
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26 Chin 3rd Road, Nantze Export Processing Zone
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